

LV-05 BGA Rework



BGA Rework station Feature :

1. Adopted with Linear slider, so all the three axles (X, Y, and Z) can do fine tuning and quick orientation with perfect positioning accuracy and speedily maneuverability.
2. Equipped with touch panel interface and PLC controlling to ensure it work stably and reliably. And it can storage multiple temperature profiling data of users. With password protection and modification function while power on. The temperature profiles will be displayed on the touch screen.
3. Three temperature zones to heat up independently, hot air heat up between up and down zones, IR heat in

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the bottom, temperature precise control is in $\pm 3^{\circ}\text{C}$.The upper temperature zone can be moved freely according to needs, the second zone can be adjusted up and down. The top and bottom heaters can be set several segments control at the same time. IR heating zone can be adjusted output power in the light of operation requirements.

4. The hot air nozzle can be rotated in 360 degree, the IR heater in the bottom can heat up the PCB board uniformly.
5. High accuracy K-type thermocouple closed-loop controlling. It can test temperature accurately through external temperature measurement interface, PCB board positioned by closed V-shape slot. The flexible and convenient universal jigs can prevent any damage or PCB deformation as well as it is suitable for all size of BGA package.
6. Large power fan to cool down the PCB quickly. The built-in vacuum pump and external vacuum nozzle is able to take BGA chips out easily.
7. Having alarm prompt function after welding is done, specially added early warning function for convenient operation.
8. It has Passed CE certificate. It is equipped with emergency stop switch and protection equipment to power off automatically when abnormal accident happened. Under this situation that temperature is out of control, circuit can automatically cut off the power with double over temperature protection function.
9. With the laser position and fast location the chip place.

BGA Rework Station Technology Parameter:

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| Total Power | 4500W |
| Upper Heating Power | 800W |
| Lower Heating Power | 1200W |
| Infrared Heating Power | 2400W (1200W is controlled) |
| Power supply | (Single Phase) AC 220V±10 50Hz |
| Location way | V-shape card slot + Universal jigs+laser position |
| Temperature Controlling | K-type thermocouple closed loop control, independent temperature control, precision up to ±3 degree |
| Electrical Material | Touch screen + Temperature control module + PLC control |
| Max PCB size | 330×310mm |
| Min PCB size | 10×10mm |
| Sensor | 1 unit |
| PCB Thickness | 0.3-5mm |
| Preheating area | 21*34cm |
| Suitable Chip Size | 1*1mm-50*50mm |
| Size | 500×530×580mm |
| Weight | Net 30kg |